



# Plating Thickness

Type	Plating Composition	Lead Frame Material	Lead Style	Plating Thickness	Typical Component Type	Lead-Free No Pb
Gold	Au over Nickel	Kovar Alloy 42	Flat	60 min. micro inch gold 1.5µm min	CQFP CERQUAD CLCC	Lead Free No Pb
Tin	Sn100	Copper Cu	Flat	200~ 600 micro-inch 5~ 16 µm	QFP SOIC SSOP TSSOP PLCC SOT	Lead Free No Pb
Tin-Bismuth	Sn97/Bi3.0	Copper Cu	Flat	200~ 600 micro-inch 5~ 16 µm	QFP SOIC SSOP TSSOP PLCC SOT	Lead Free No Pb
Tin-Copper	Sn98/Cu2.0	Copper Cu	Flat	200~ 600 micro-inch 5~ 16 µm	QFP SOIC SSOP TSSOP PLCC SOT	Lead Free No Pb
Tin-Lead	Sn85/Pb15	Copper Cu	Flat	200~ 600 micro-inch 5~ 16 µm	QFP SOIC SSOP TSSOP PLCC SOT	-
Tin-Silver	Sn96.5/Ag3.5	Gold	Sphere	-	BGA CSP	Lead Free No Pb
Tin-Silver-Copper	Sn95.5/Ag4.0/Cu0.5 to Sn95.5/Ag3.5/Cu1.0	Gold	Sphere	-	BGA CSP	Lead Free No Pb

Notes: "Plating" is also known as "lead-finish".

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